

To our customers,

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## Old Company Name in Catalogs and Other Documents

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On April 1<sup>st</sup>, 2010, NEC Electronics Corporation merged with Renesas Technology Corporation, and Renesas Electronics Corporation took over all the business of both companies. Therefore, although the old company name remains in this document, it is a valid Renesas Electronics document. We appreciate your understanding.

Renesas Electronics website: <http://www.renesas.com>

April 1<sup>st</sup>, 2010  
Renesas Electronics Corporation

Issued by: Renesas Electronics Corporation (<http://www.renesas.com>)

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Not recommended  
for new design

## Notice

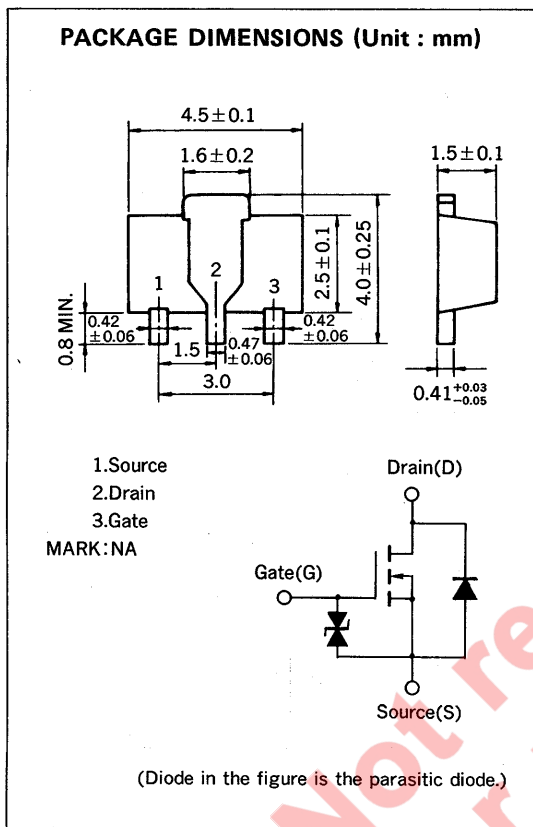
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MOS FIELD EFFECT TRANSISTOR  
2SK1273

N-CHANNEL MOS FET  
FOR HIGH SPEED SWITCHING



The 2SK1273, N-channel vertical type MOS FET, is a switching device which can be driven directly by the output of ICs having a 5 V power source.

As the MOS FET has low on-state resistance and excellent switching characteristics, it is suitable for driving actuators such as motors, relays, and solenoids.

**FEATURES**

- Directly driven by ICs having a 5 V power source.
- Has low on-state resistance  
 $R_{DS(on)} = 1.00 \Omega \text{ MAX. @ } V_{GS} = 4.0 \text{ V, } I_D = 0.5 \text{ A}$   
 $R_{DS(on)} = 0.65 \Omega \text{ MAX. @ } V_{GS} = 10 \text{ V, } I_D = 0.5 \text{ A}$
- Not necessary to consider driving current because of its high input impedance.
- Possible to reduce the number of parts by omitting the bias resistor.

**QUALITY GRADE**

Standard

Please refer to "Quality grade on NEC Semiconductor Devices" (Document number IEI-1209) published by NEC Corporation to know the specification of quality grade on the devices and its recommended applications.

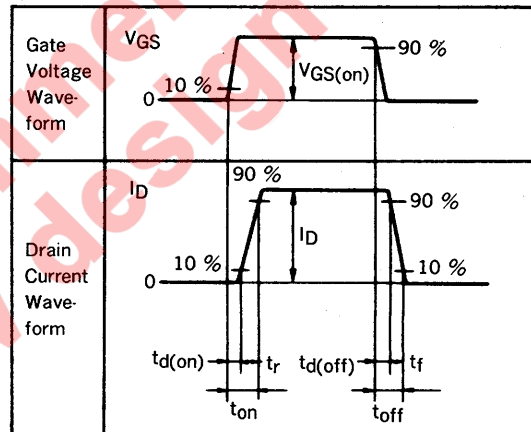
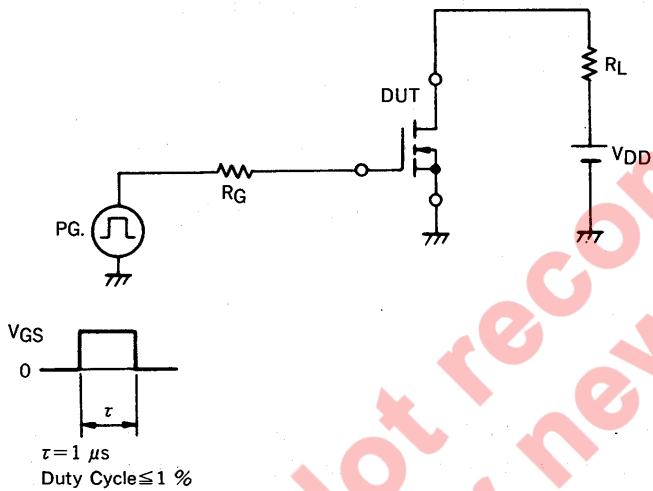
**ABSOLUTE MAXIMUM RATINGS ( $T_a = 25^\circ\text{C}$ )**

PARAMETER	SYMBOL	RATINGS	UNIT	TEST CONDITIONS
Drain to Source Voltage	$V_{DSS}$	60	V	$V_{GS} = 0$
Gate to Source Voltage	$V_{GSS}$	$\pm 20$	V	$V_{DS} = 0$
Drain Current	$I_D(\text{DC})$	$\pm 2.0$	A	
Drain Current	$I_D(\text{pulse})$	$\pm 4.0$	A	$PW \leq 10 \text{ ms, Duty Cycle} \leq 50 \%$
Total Power Dissipation	$P_T$	2.0	W	when using ceramic board of $16 \text{ cm}^2 \times 0.7 \text{ mm}$
Channel Temperature	$T_{ch}$	150	$^\circ\text{C}$	
Storage Temperature	$T_{stg}$	-55 to +150	$^\circ\text{C}$	

ELECTRICAL CHARACTERISTICS (T<sub>a</sub> = 25 °C)

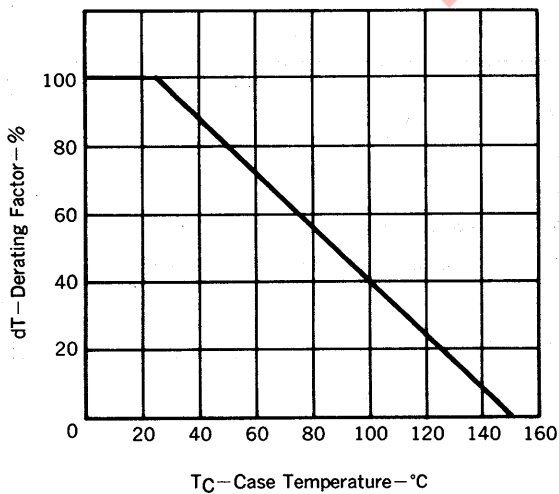
PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNIT	TEST CONDITIONS
Drain Cut-off Current	I <sub>DSS</sub>			10	μA	V <sub>DS</sub> = 60 V, V <sub>GS</sub> = 0
Gate Leakage Current	I <sub>GSS</sub>			±10	μA	V <sub>GS</sub> = ±20 V, V <sub>DS</sub> = 0
Gate Cut-off Voltage	V <sub>GS(off)</sub>	1.0	1.7	2.5	V	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA
Forward Transfer Admittance	y <sub>fs</sub>	0.4			S	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 0.5 A
Drain to Source On-State Resistance	R <sub>DS(on)1</sub>		0.31	1.00	Ω	V <sub>GS</sub> = 4.0 V, I <sub>D</sub> = 0.5 A
Drain to Source On-State Resistance	R <sub>DS(on)2</sub>		0.24	0.65	Ω	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 0.5 A
Input Capacitance	C <sub>iss</sub>		220		pF	V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0, f = 1 MHz
Output Capacitance	C <sub>oss</sub>		105		pF	
Feedback Capacitance	C <sub>rss</sub>		16		pF	
Turn-On Delay Time	t <sub>d(on)</sub>		15		ns	V <sub>GS(on)</sub> = 10 V, R <sub>G</sub> = 10 Ω V <sub>DD</sub> = 25 V, I <sub>D</sub> = 0.5 A R <sub>L</sub> = 50 Ω
Rise Time	t <sub>r</sub>		35		ns	
Turn-Off Delay Time	t <sub>d(off)</sub>		380		ns	
Fall Time	t <sub>f</sub>		120		ns	

SWITCHING TIME MEASUREMENT CIRCUIT AND CONDITIONS

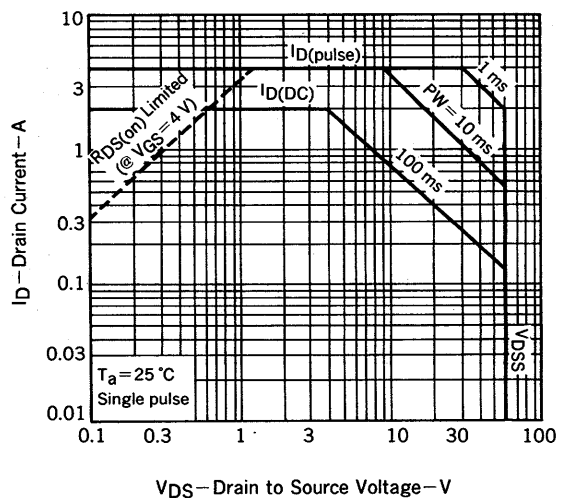


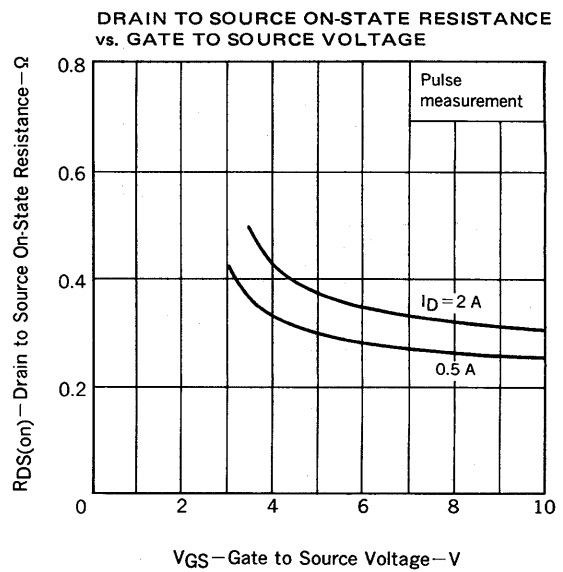
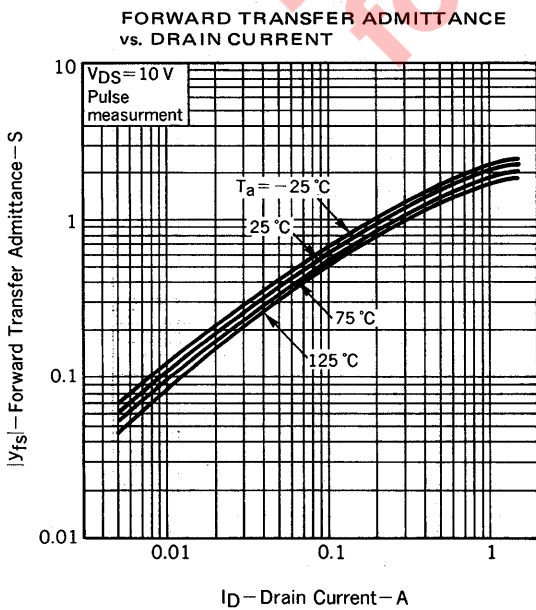
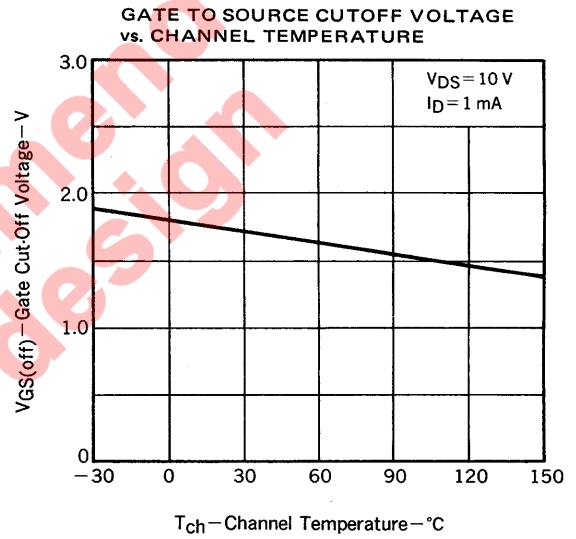
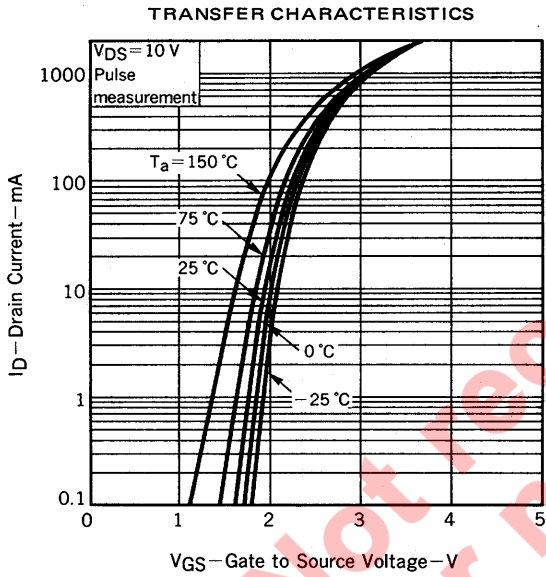
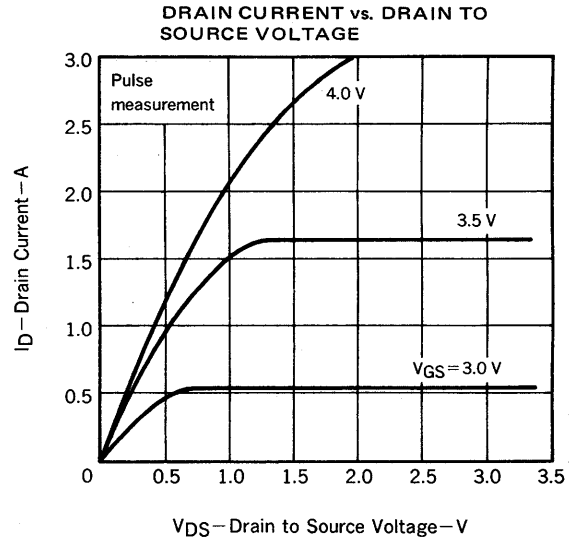
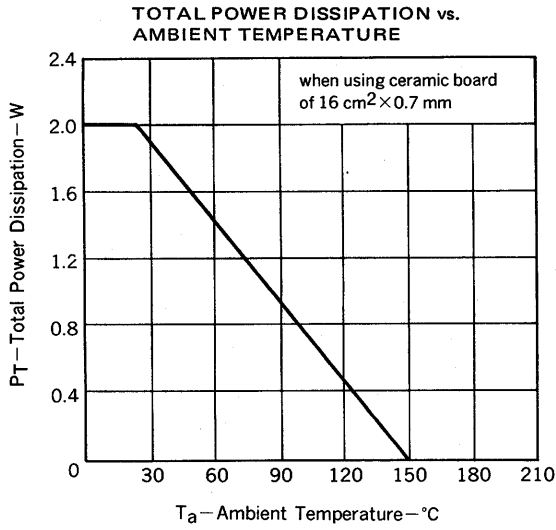
TYPICAL CHARACTERISTICS (T<sub>a</sub> = 25 °C)

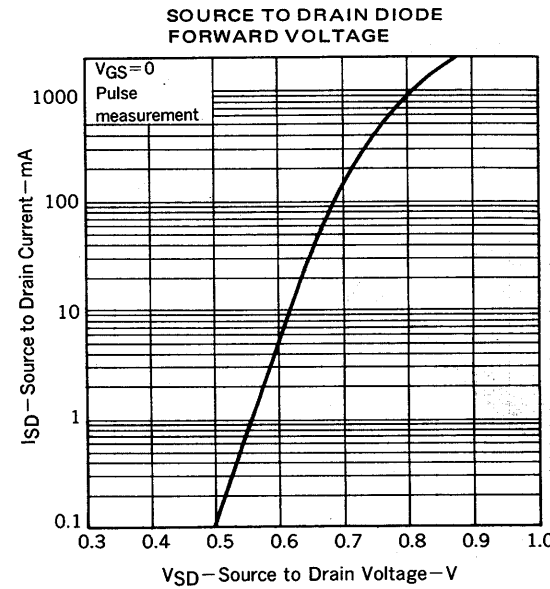
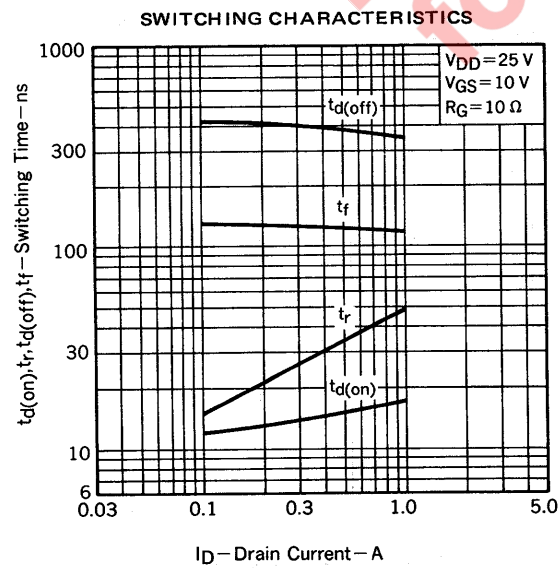
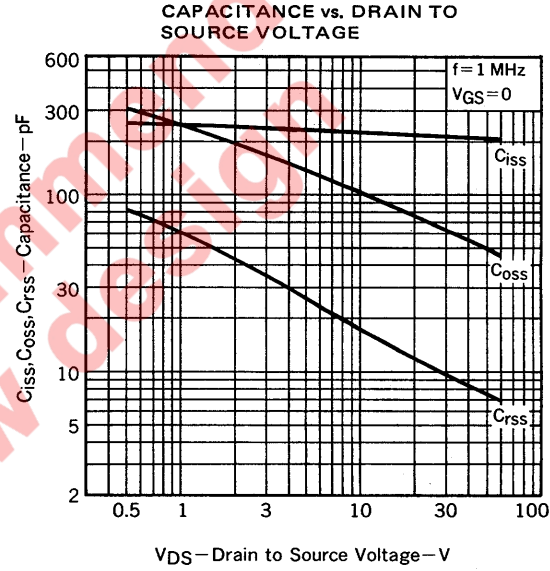
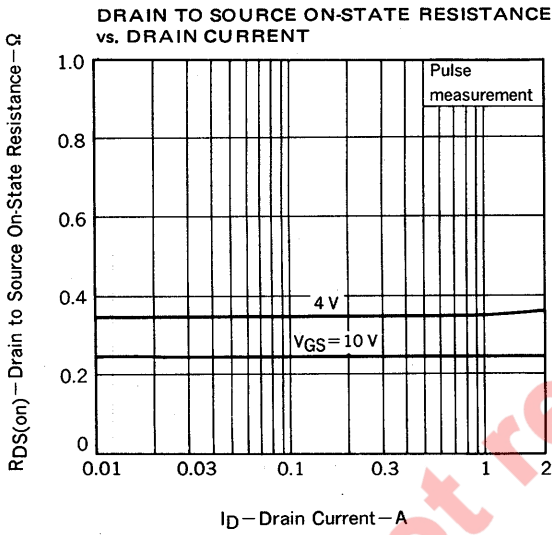
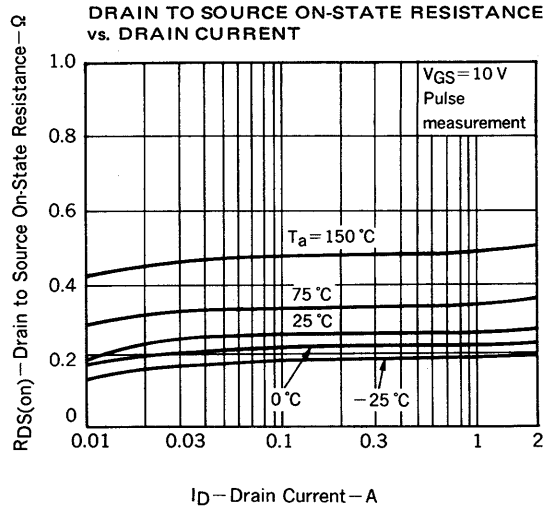
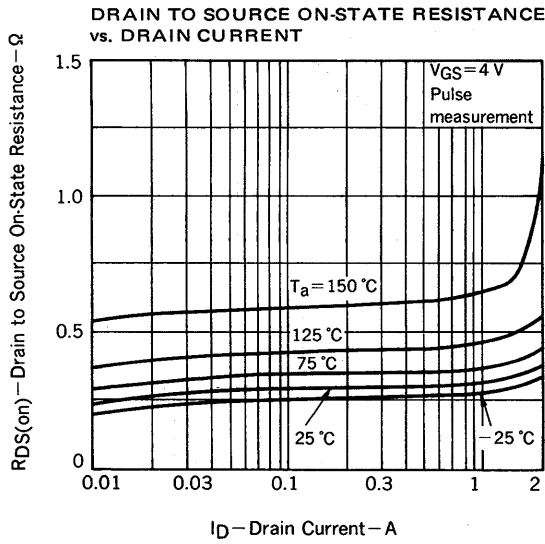
DERATING FACTOR OF FORWARD BIAS SAFE OPERATING AREA



FORWARD BIAS SAFE OPERATING AREA







**RECOMMENDED SOLDERING CONDITIONS**

Mounting of this product by soldering should be done under the following conditions.  
Please consult our representatives about soldering methods and conditions other than these.

**SURFACE MOUNT TYPE**

For details of the recommended soldering conditions, see the information document.  
"Device Mounting Manual for Surface Mounting (IEI-1207)."

Soldering Method	Soldering Conditions	Symbol for Recommended Conditions
Infrared Reflow	Package peak temp.: 230 °C Soldering time: within 30 sec (above 210 °C) Soldering times: 1, Days limitation: none*	IR30-00
Vapor Phase Soldering	Package peak temp.: 215 °C Soldering time: within 40 sec (above 200 °C) Soldering times: 1, Days limitation: none*	VP15-00
Wave Soldering	Soldering bath temp.: below 260 °C Soldering time: within 10 sec Soldering times: 1, Days limitation: none*	WS60-00

\*: Stored days under storage conditions at 25 °C and below 65 % R.H. after the dry-pack has been opened.

**Note 1** Combination of soldering methods should be avoided.

**REFERENCE**

Document Name	Document No.
NEC semiconductor device reliability/quality control system.	TEI-1202
Quality grade on NEC semiconductor devices.	IEI-1209
Semiconductor device mounting technology manual.	IEI-1207
Semiconductor device package manual.	IEI-1213
Guide to quality assurance for semiconductor devices.	MEI-1202
Semiconductor selection guide.	MF-1134



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